US00D588078S

(12) **United States Design Patent**
Okada et al.

(10) **Patent No.: US D588,078 S**
(45) **Date of Patent: ** Mar. 10, 2009**

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(54) **HEAT DISSIPATION DETERRENCE LINK FOR SEMICONDUCTOR MANUFACTURE**

(75) Inventors: **Mitsuhiro Okada**, Tokyo (JP); **Yoshikazu Furusawa**, Tokyo (JP); **Daisuke Suzuki**, Tokyo (JP)

(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/270,120**

(22) Filed: **Dec. 15, 2006**

(30) **Foreign Application Priority Data**

Jun. 16, 2006 (JP) 2006-015663

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** D13/182; D8/16; D23/386; 118/724, 725; 432/241, 432/242; 438/680
See application file for complete search history.

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Mitsuhiro Okada, et al. entitled Heat Dissipation Deterrence Link for Semiconductor Manufacture.

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Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Smith, Gambrell & Russell, LLP

(57) **CLAIM**

The ornamental design for a heat dissipation deterrence link for semiconductor manufacture, as shown and described.

DESCRIPTION

FIG. **1** is a front view of the design for a heat dissipation deterrence link for semiconductor manufacture in accordance with the invention;

FIG. **2** is a rear view thereof;

FIG. **3** is a right side view thereof;

FIG. **4** is a left side view thereof;

FIG. **5** is a plan view thereof;

FIG. **6** is a bottom view thereof;

FIG. **7** is a sectional view thereof along A—A of FIG. **1**;

FIG. **8** is a perspective view thereof; and,

FIG. **9** shows a heat dissipation deterrence link for semiconductor manufacture in accordance with the invention in use.

In practice, a heat dissipation deterrence link is placed on the bottom of a thermostat plug that is included in a process tube for semiconductor manufacture. Then, in use, the link suppresses heat from a bottom sub-heater. Preferably, the heat dissipation deterrence link for semiconductor manufacture in accordance with the present invention is fabricated from quartz.

The broken line showing the environment is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 7 Drawing Sheets

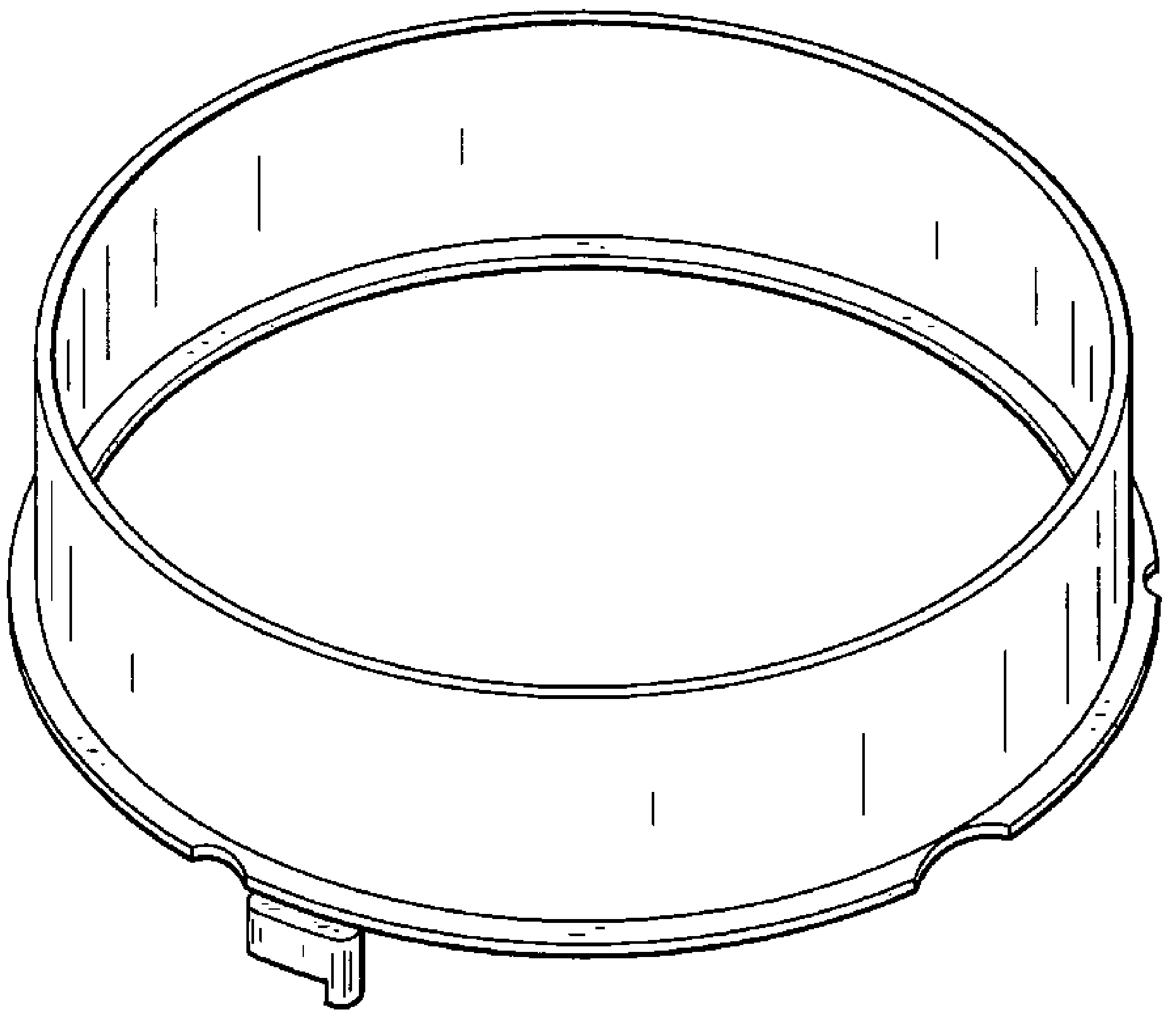

FIG. 1

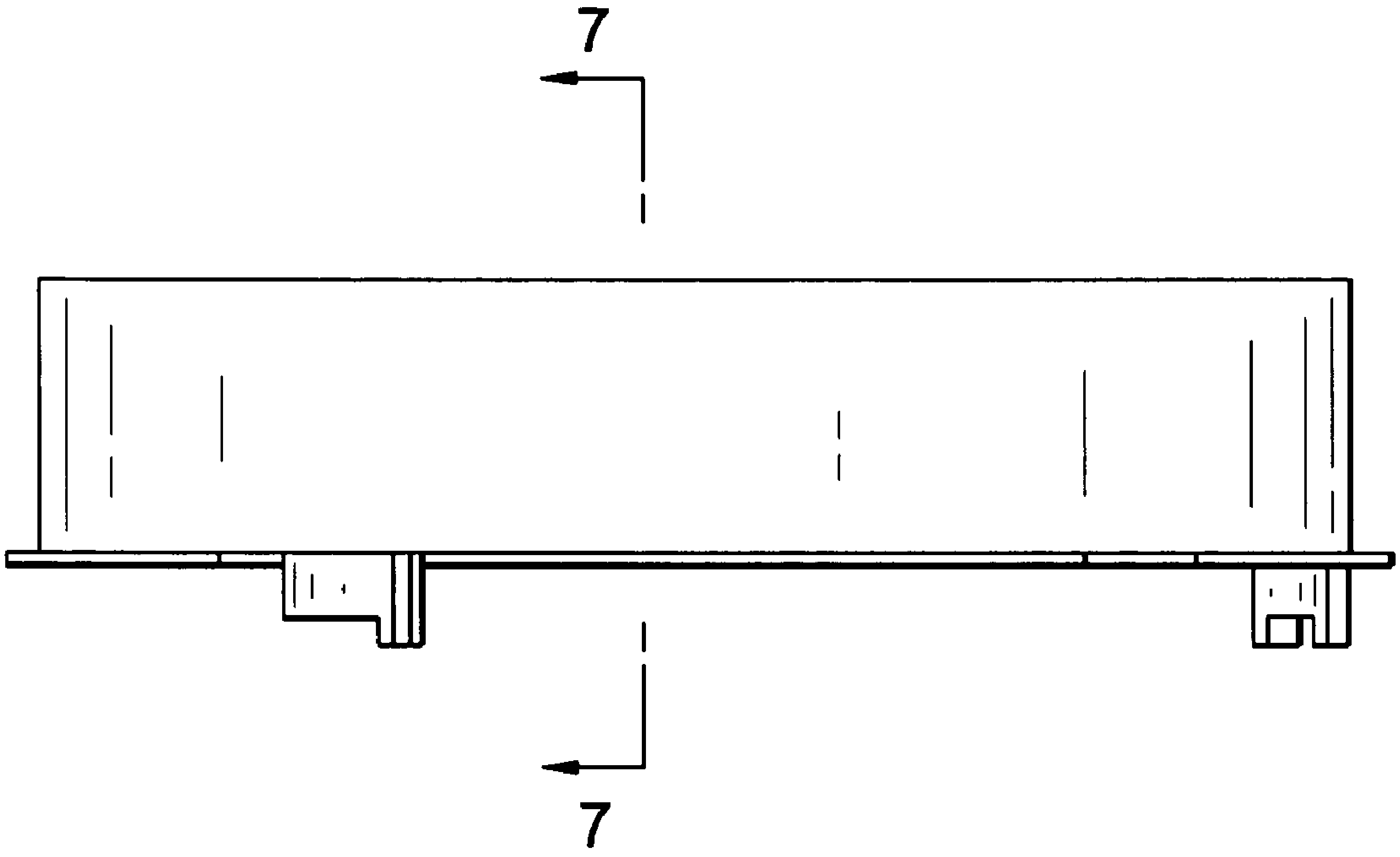

FIG. 2

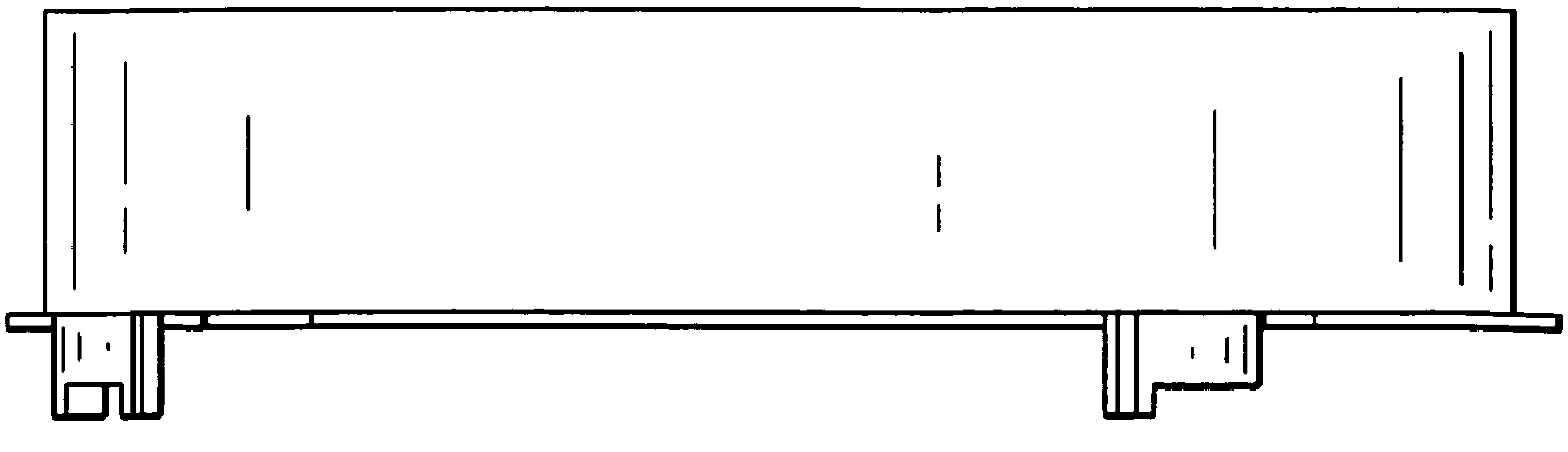

FIG. 3

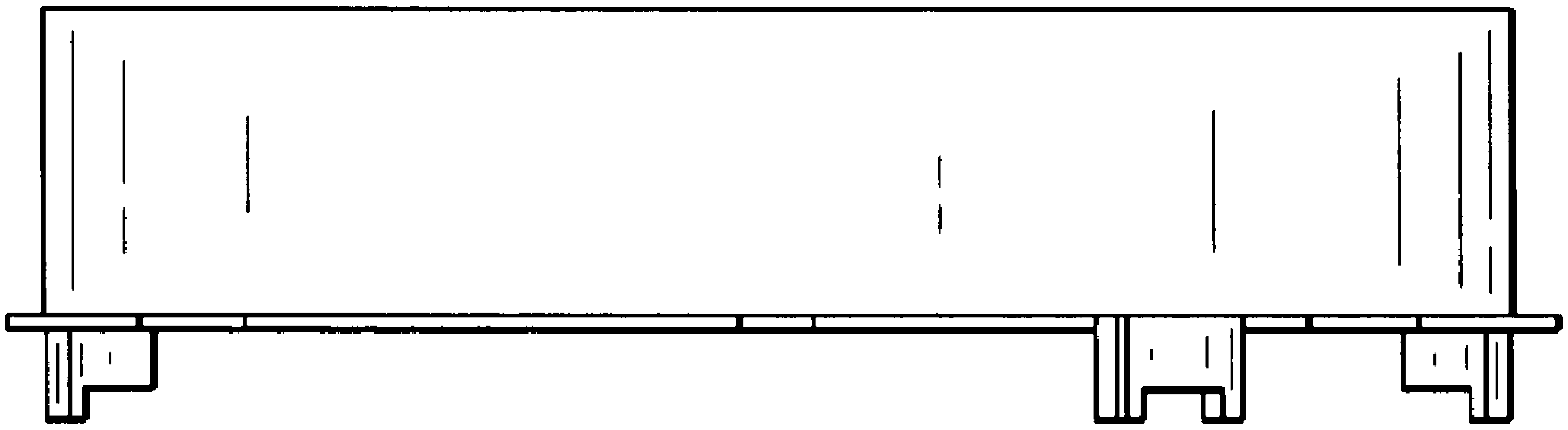

FIG. 4

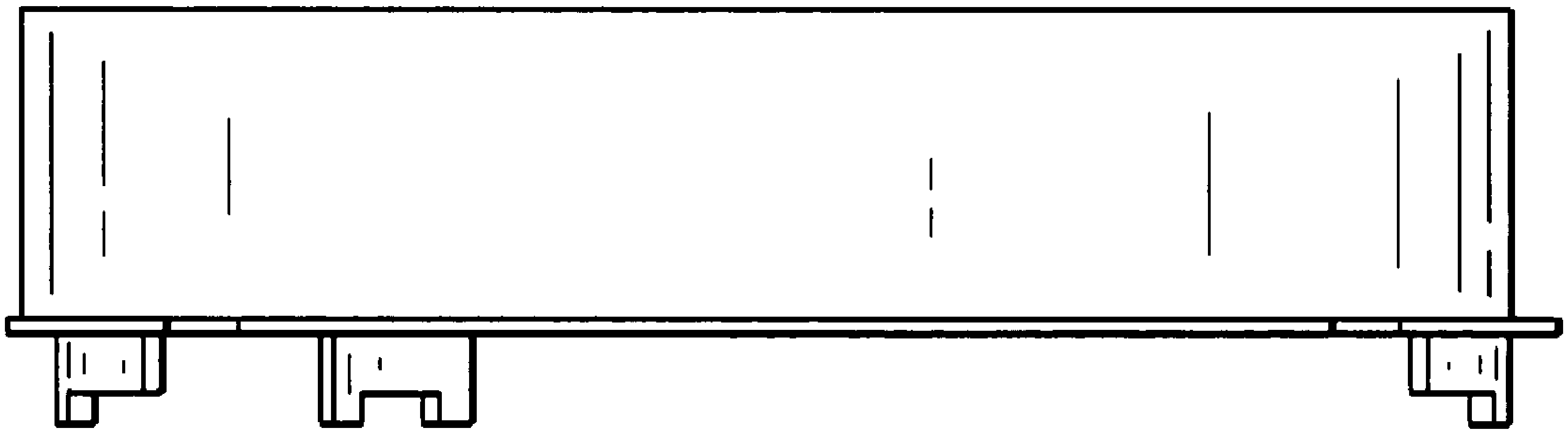

FIG. 5

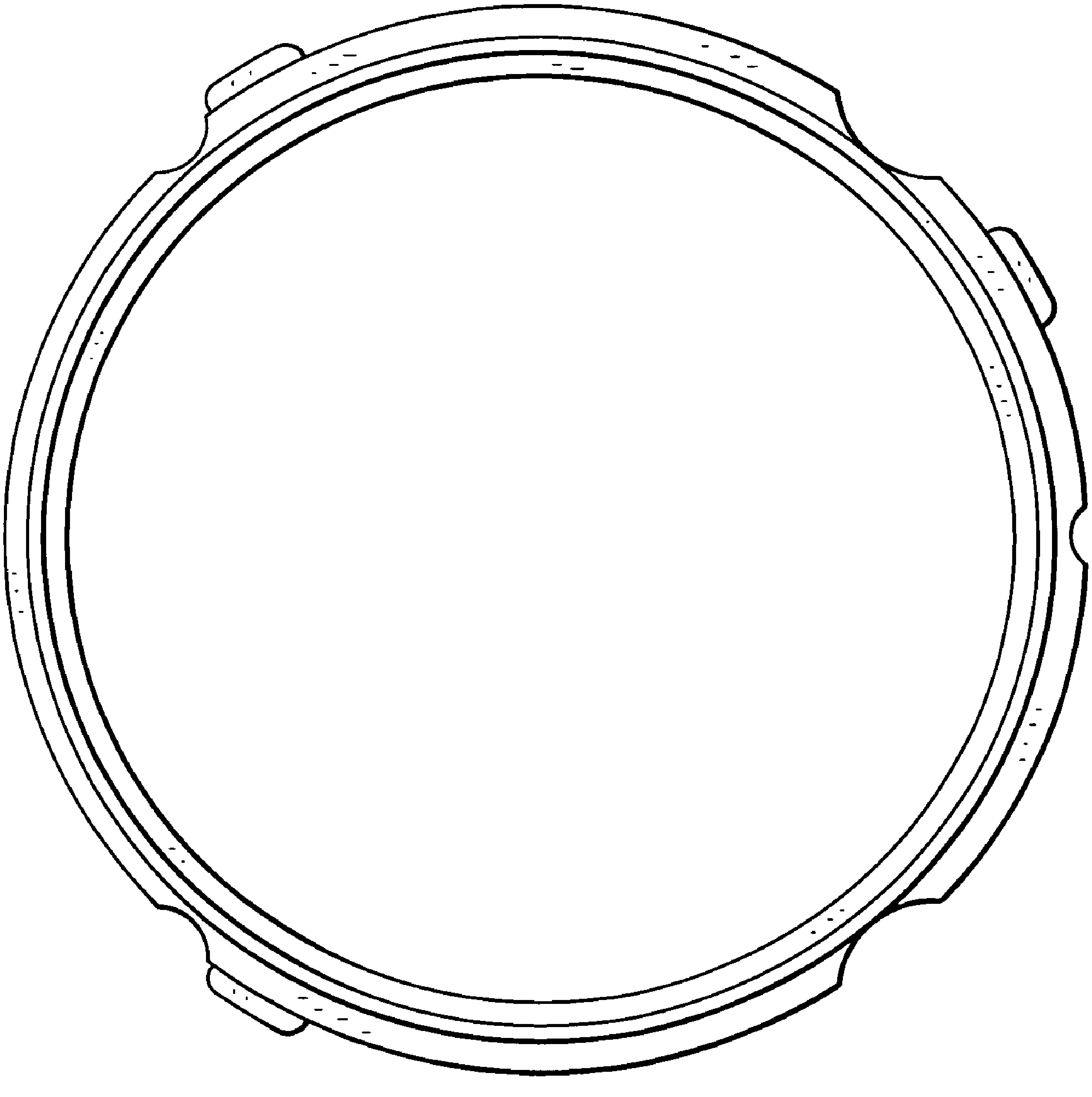

FIG. 6

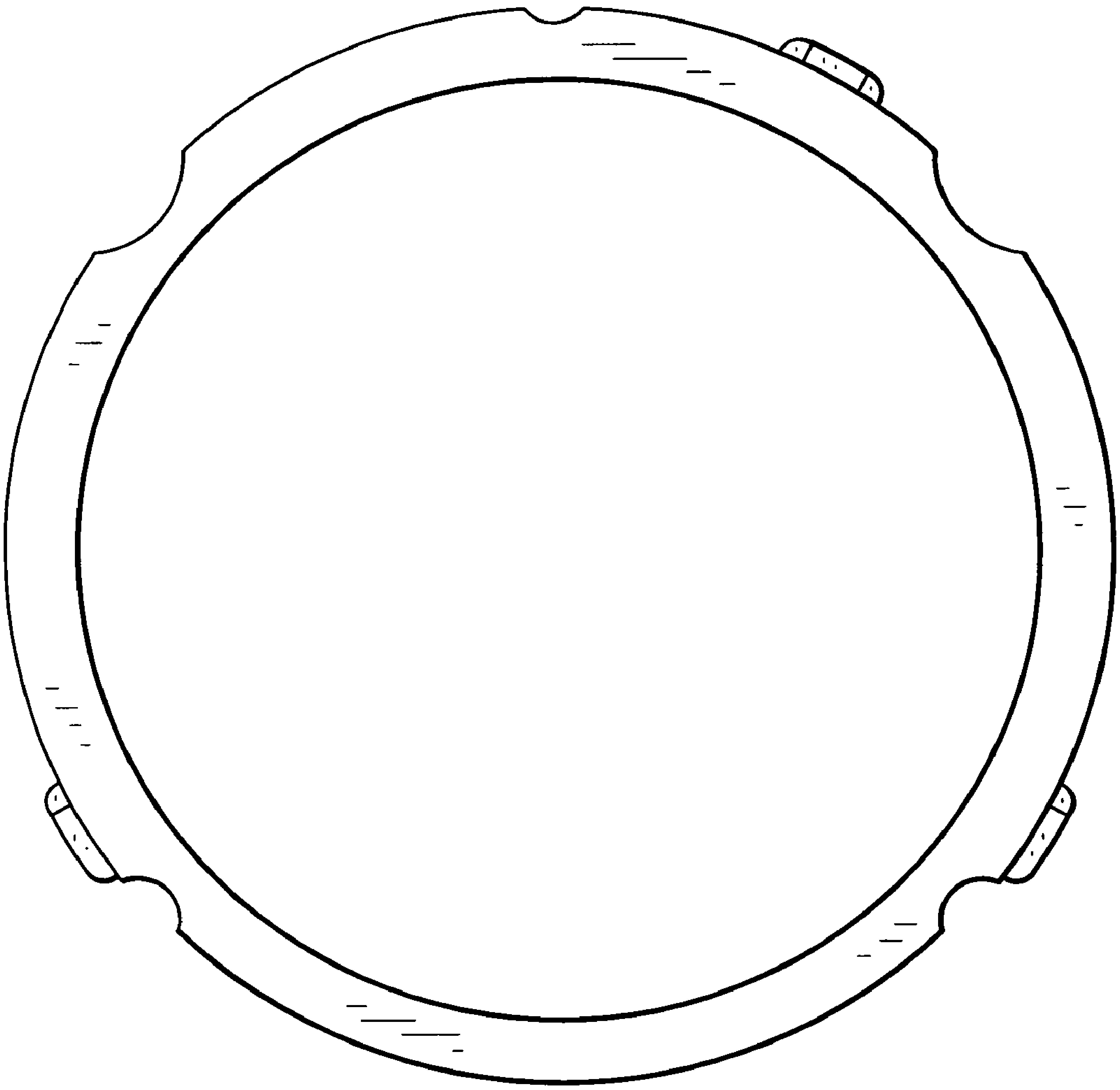

FIG. 7

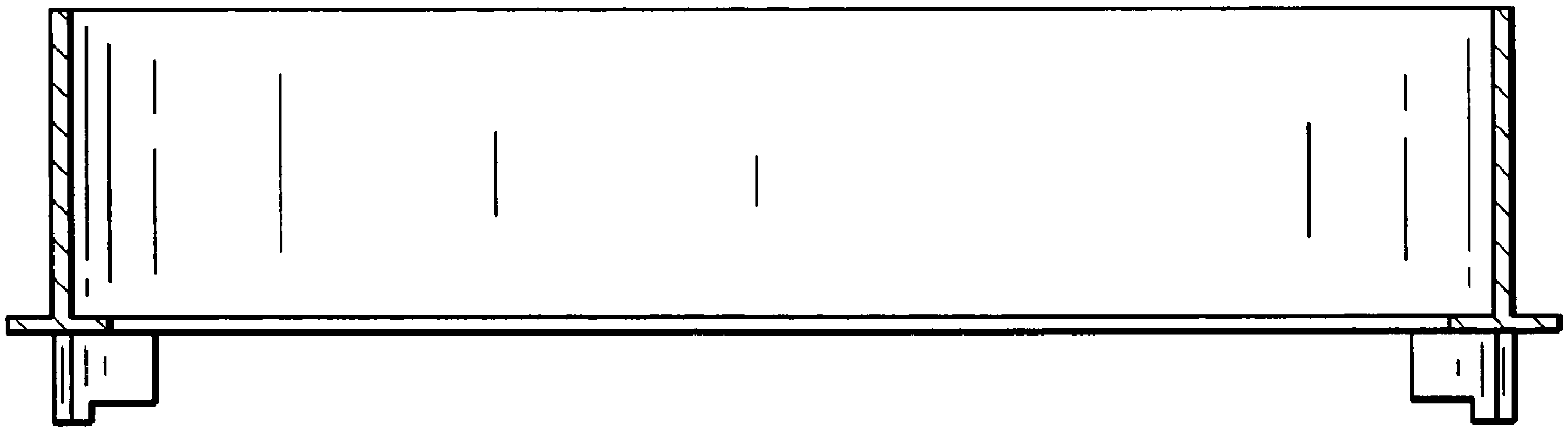

FIG. 8

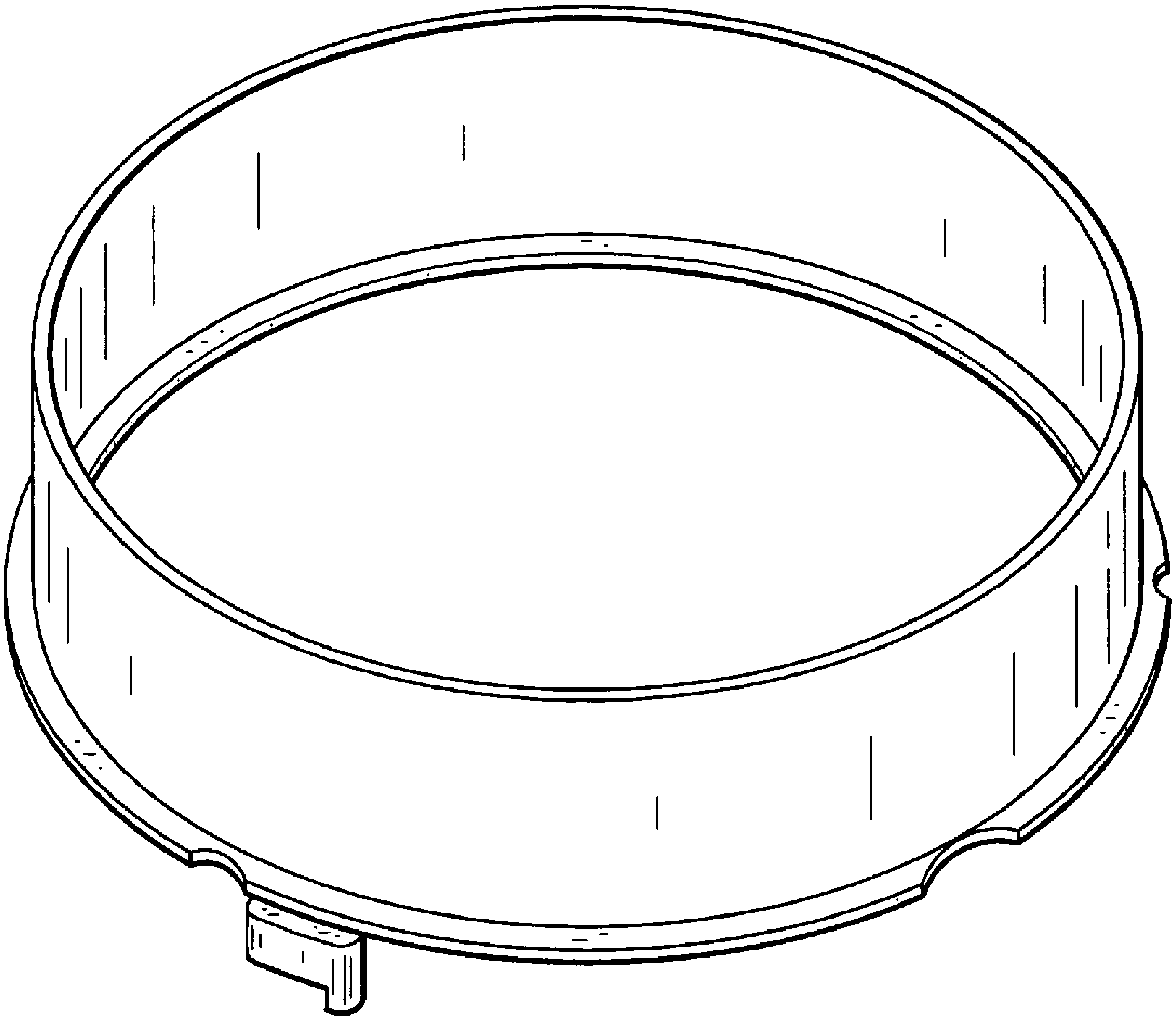

FIG. 9